

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims

1-16. cancelled

17. (currently amended) A micro-electro-mechanical system (MEMS) package for hermetically sealing a MEMS device, comprising:

the MEMS package having a fill port, wherein the fill port is a through hole capable of having at least one medium inserted through the fill port;

at least one low temperature curing sealant placed within the fill port wherein the at least one low temperature curing sealant substantially fills the fill port; and

a metal cap placed over the at least one low temperature curing sealant in a specific pattern wherein the metal cap substantially hermetically seals the fill port.

18. (original) A MEMS package as in claim 17, further comprising a MEMS device placed within the MEMS package.

19. (original) A MEMS package as in claim 18, further comprising a bond ring surrounding the MEMS device.

20. (original) A MEMS package as in claim 19, wherein the fill port is located in a break in the bond ring.

21. (original) A MEMS package as in claim 17, further comprising a lid disposed above the bond ring.
22. (original) A MEMS package as in claim 21, wherein the fill port is a through-hole located in the lid.
23. (original) A MEMS package as in claim 21, wherein the lid is selected from the group of materials consisting of glass and silicon.
24. (currently amended) A MEMS package as in claim 17, wherein the ~~one or more~~at least one low temperature curing sealants placed within the fill ~~hole~~port is an organic sealant selected from the group consisting of thermal-set epoxy, UV curable epoxy, two-part epoxy, silicone, and spin-on polyamides.
25. (currently amended) A MEMS package as in claim 17, wherein the at least one low temperature curing sealant is an inorganic sealant.
26. (original) A MEMS package as in claim 17, wherein the at least one medium is a gas selected from the group of media consisting of air, nitrogen, oxygen, and argon.

27. (original) A MEMS package as in claim 17, wherein the at least one medium is a liquid selected from the group of liquid media consisting of a low vapor pressure oil, a lubricant, and a hydrophobic fluid.

28. (original) A MEMS package as in claim 27, wherein the liquid refractive index is similar to a lid refractive index.

29. (original) A MEMS package as in claim 27, wherein the liquid has a coefficient of thermal expansion similar to that of the MEMS device.

30. (original) A MEMS package as in claim 17, wherein the at least one medium is a solid selected from the group of solid media consisting of sol gel.

31. (currently amended) A MEMS package as in claim 17, wherein the at least one low temperature curing sealant is cured using a low temperature curing process and the MEMS package is cleaned, wherein the low temperature curing process occurs at a temperature less than 100 degrees Celsius.

32. (currently amended) A MEMS package as in claim 17, wherein the metal cap is formed over the at least one low temperature curing sealant using a low temperature process selected from the group consisting of electron beam deposition and physical vapor deposition.

33. (original) A MEMS package as in claim 17, comprising a metal cap made from one or more types of metal, said one or more types of metal selected from the group consisting of gold, titanium, silver, aluminum, chromium, and tantalum.

34. (currently amended) A micro-electro-mechanical system (MEMS) package for hermetically sealing a MEMS device, comprising:

a means for filling a MEMS package through a fill port with at least one medium;

a means for plugging the fill port in the MEMS package with at least one low temperature curing sealant; and

a means for hermetically sealing a metal cap in a specific pattern over the at least one low temperature curing sealant.